

# 2SK1404 Silicon N Channel MOS FET

REJ03G0944-0300 Rev.3.00 May 15, 2006

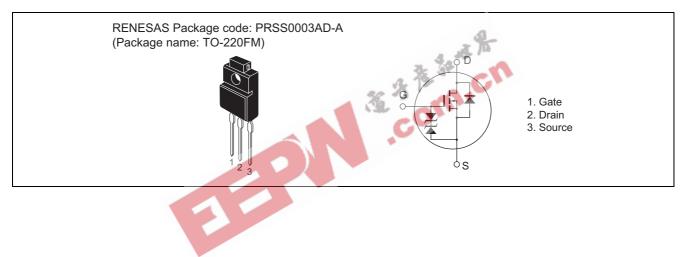
## Application

High speed power switching

### Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator and DC-DC converter

### Outline





# **Absolute Maximum Ratings**

			(1a = 25 C)
Item	Symbol	Ratings	Unit
Drain to source voltage	V <sub>DSS</sub>	600	V
Gate to source voltage	V <sub>GSS</sub>	±30	V
Drain current	ID	5	A
Drain peak current	I <sub>D(pulse)</sub> *1	20	A
Body to drain diode reverse drain current	I <sub>DR</sub>	5	A
Channel dissipation	Pch <sup>*2</sup>	35	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW  $\leq$  10  $\mu$ s, duty cycle  $\leq$ 1%

2. Value at  $T_C = 25^{\circ}C$ 

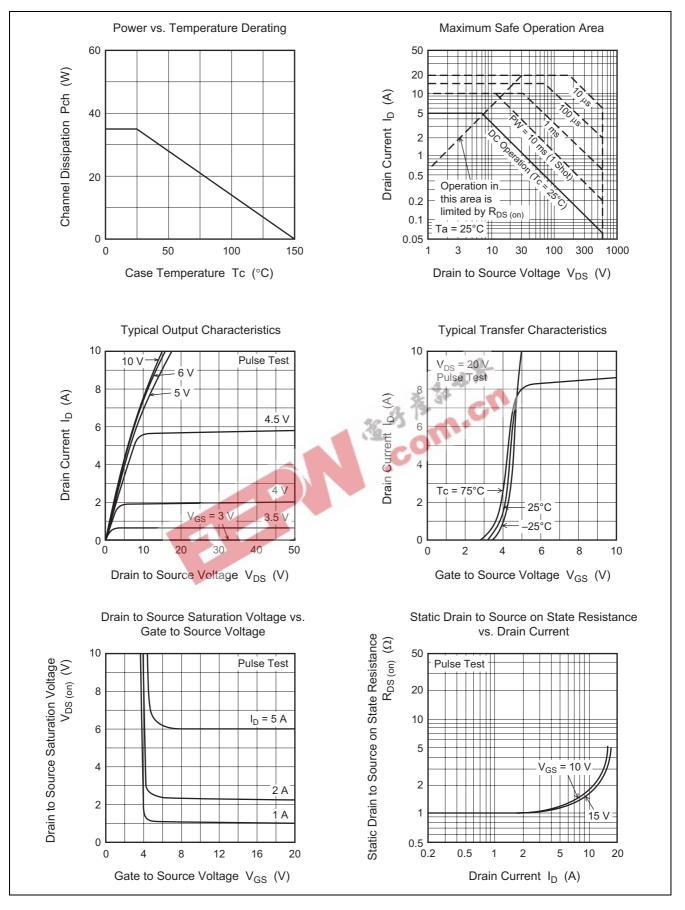
# **Electrical Characteristics**

						$(Ta = 25^{\circ}C)$
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	V <sub>(BR)DSS</sub>	600	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V <sub>(BR)GSS</sub>	±30	_	—	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I <sub>GSS</sub>	_	_	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I <sub>DSS</sub>	_	_	250	μΑ	$V_{DS} = 500 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V <sub>GS(off)</sub>	2.0	_	3.0	V	$I_{D} = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state	R <sub>DS(on)</sub>	_	1.1	1.5	Ω	$I_{\rm D}$ = 2.5 A, V <sub>GS</sub> = 10 V * <sup>3</sup>
resistance			- %C	2		
Forward transfer admittance	y <sub>fs</sub>	3.0	5.0	-0	S	$I_D = 2.5 \text{ A}, V_{DS} = 10 \text{ V}^{*3}$
Input capacitance	Ciss	-	<b>10</b> 00	0	pF	$V_{DS} = 10 V, V_{GS} = 0,$
Output capacitance	Coss	-+	250	_	рF	f = 1 MHz
Reverse transfer capacitance	Crss		45	—	рF	
Turn-on delay time	t <sub>d(on)</sub>		12	—	ns	$I_D = 2.5 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time	tr	-	45	—	ns	$R_L = 12 \Omega$
Turn-off delay time	t <sub>d(off)</sub>	_	105	—	ns	
Fall time	t <sub>f</sub>	_	55	_	ns	
Body to drain diode forward voltage	V <sub>DF</sub>	—	0.9	—	V	I <sub>F</sub> = 5 A, V <sub>GS</sub> = 0
Body to drain diode reverse recovery time	t <sub>rr</sub>	_	500	_	ns	I <sub>F</sub> = 5 A, V <sub>GS</sub> = 0, di <sub>F</sub> /dt = 100 A/μs

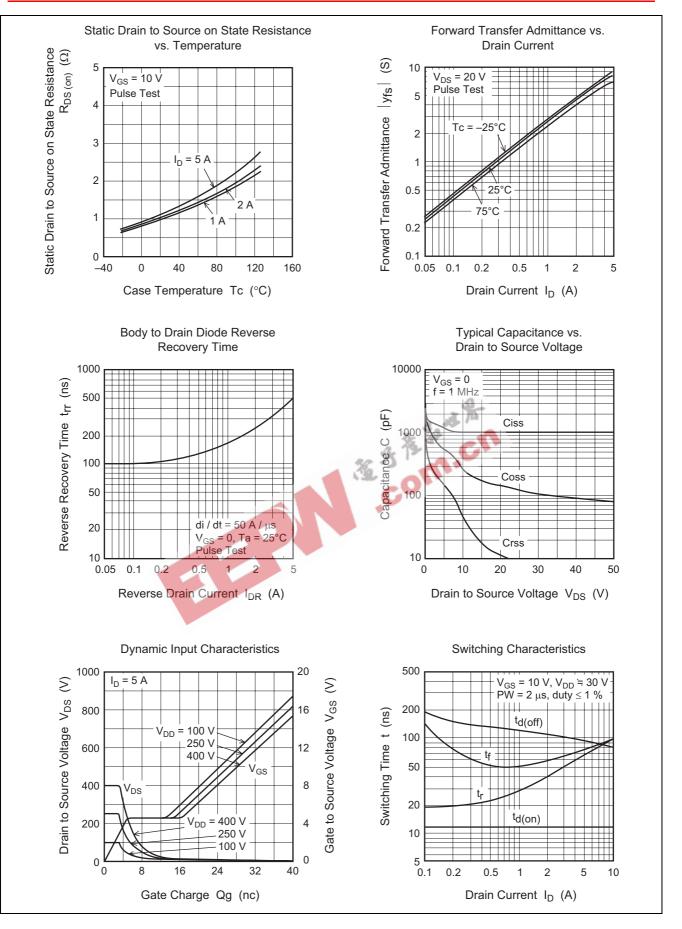
Note: 3. Pulse test



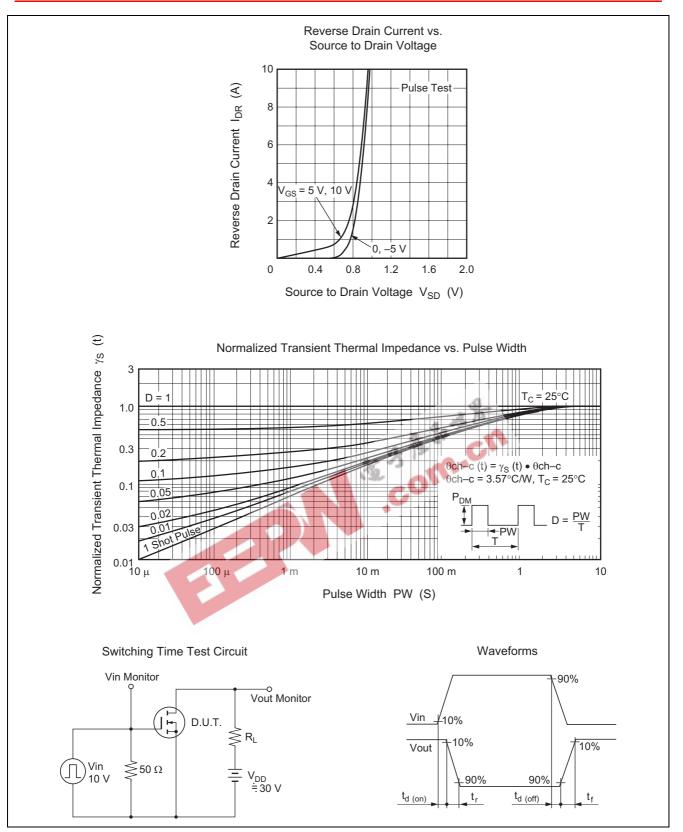
### **Main Characteristics**





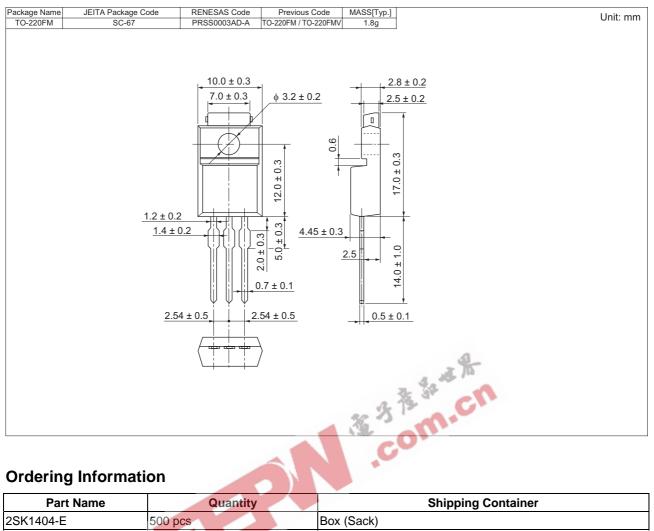








### **Package Dimensions**



Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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